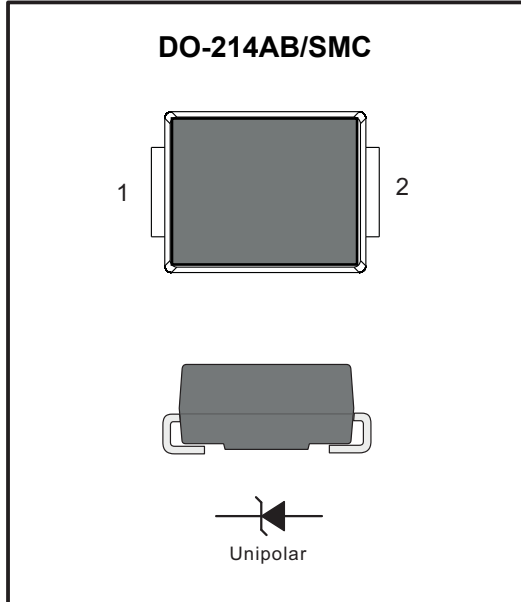


## PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1   | Cathode     |
| 2   | Anode       |



## FEATURES

- ◆ For surface mounted applications
- ◆ Low profile package
- ◆ Glass Passivated Chip Junction
- ◆ Easy to pick and place
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives

## MECHANICAL DATA

- ◆ Case: SMC
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 0.22g / 0.0077oz

## Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

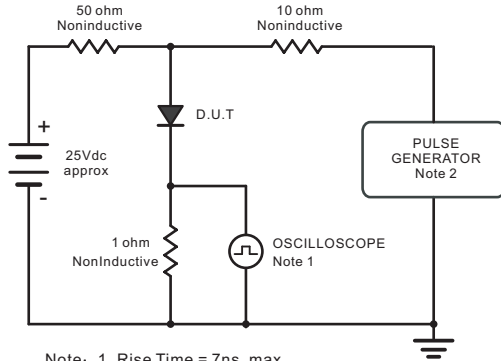
| Parameter  | Symbols                            | ES3A       | ES3B | ES3C | ES3D | ES3E | ES3G | ES3J | Units              |
|--|------------------------------------|------------|------|------|------|------|------|------|--------------------|
| Maximum Repetitive Peak Reverse Voltage  | $V_{RRM}$                          | 50         | 100  | 150  | 200  | 300  | 400  | 600  | V                  |
| Maximum RMS voltage  | $V_{RMS}$                          | 35         | 70   | 105  | 140  | 210  | 280  | 420  | V                  |
| Maximum DC Blocking Voltage  | $V_{DC}$                           | 50         | 100  | 150  | 200  | 300  | 400  | 600  | V                  |
| Maximum Average Forward Rectified Current at $T_c = 125\text{ }^\circ\text{C}$   | $I_{F(AV)}$                        | 3          |      |      |      |      |      |      | A                  |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load   | $I_{FSM}$                          | 90         |      |      |      |      |      |      | A                  |
| Maximum Forward Voltage at 3 A   | $V_F$                              | 1          |      |      |      | 1.25 |      | 1.68 | V                  |
| Maximum DC Reverse Current at Rated DC Blocking Voltage<br>$T_a = 25\text{ }^\circ\text{C}$<br>$T_a = 125\text{ }^\circ\text{C}$ | $I_R$                              | 5<br>100   |      |      |      |      |      |      | $\mu\text{A}$      |
| Typical Junction Capacitance at $V_R = 4\text{V}$ , $f = 1\text{MHz}$  | $C_j$                              | 40         |      |      |      |      |      |      | pF                 |
| Maximum Reverse Recovery Time <sup>(1)</sup>   | $t_{rr}$                           | 35         |      |      |      |      |      |      | ns                 |
| Typical Thermal Resistance <sup>(2)</sup>  | $R_{\theta JA}$<br>$R_{\theta JC}$ | 40<br>16   |      |      |      |      |      |      | $^\circ\text{C/W}$ |
| Operating and Storage Temperature Range  | $T_j, T_{stg}$                     | -55 ~ +150 |      |      |      |      |      |      | $^\circ\text{C}$   |

(1) Measured with  $I_F = 0.5\text{ A}$ ,  $I_R = 1\text{ A}$ ,  $I_{rr} = 0.25\text{ A}$ .

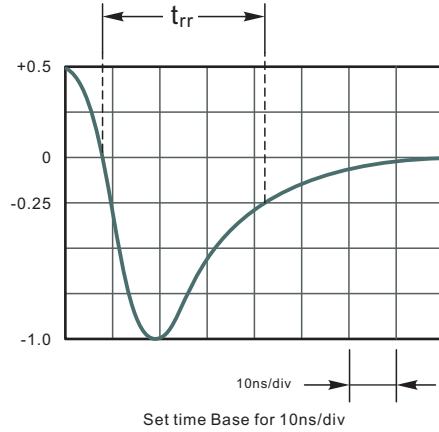
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

## Typical Characteristics

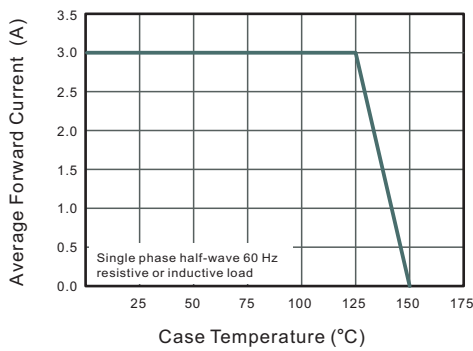
**Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram**



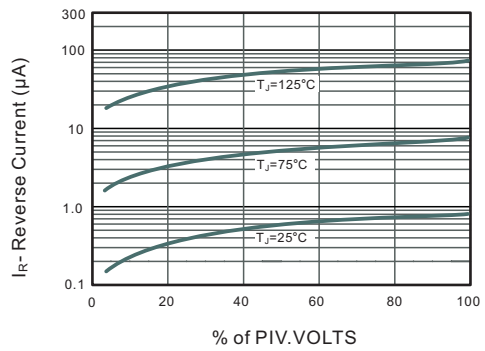
Note: 1. Rise Time = 7ns, max.  
Input Impedance = 1megohm, 22pF.  
2. Rise Time = 10ns, max.  
Source Impedance = 50 ohms.



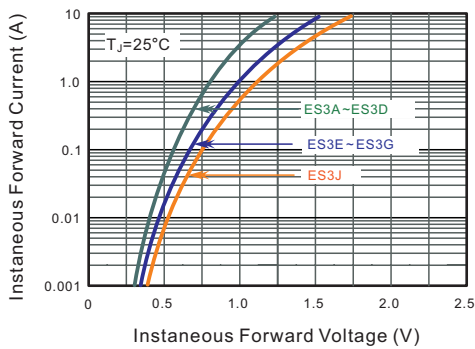
**Fig.2 Maximum Average Forward Current Rating**



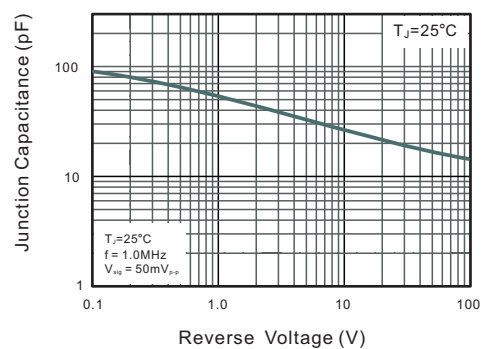
**Fig.3 Typical Reverse Characteristics**



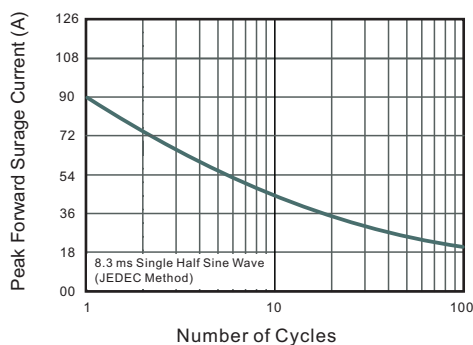
**Fig.4 Typical Forward Characteristics**



**Fig.5 Typical Junction Capacitance**



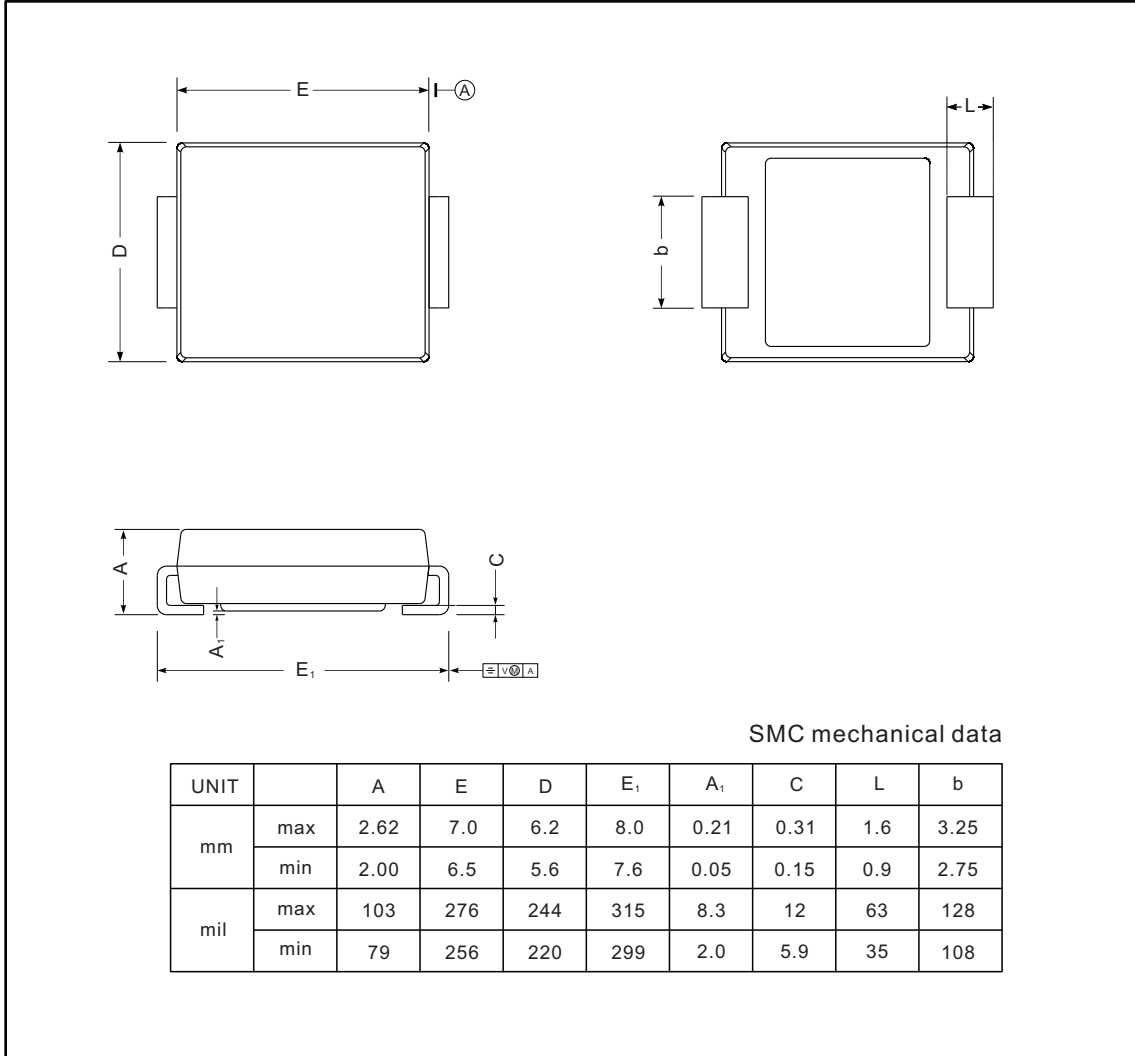
**Fig.6 Maximum Non-Repetitive Peak Forward Surge Current**



**PACKAGE OUTLINE**

Plastic surface mounted package; 2 leads

SMC



**The recommended mounting pad size**

